

Features

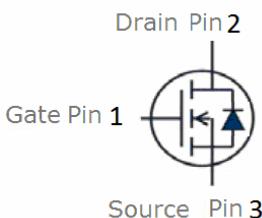
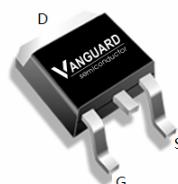
- N-Channel
- Enhancement mode
- Very low on-resistance @ $V_{GS}=4.5$ V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant



Halogen-Free

V_{DS}	150	V
$R_{DS(on),typ}@VGS=10V$	125	mΩ
$R_{DS(on),typ}@VGS=4.5V$	115	mΩ
I_D	10	A

TO-252



Part ID	Package Type	Marking	Tape and reel information
VSD140N15MS	TO-252	140N15M	2500pcs/reel

Maximum ratings, at $T_j=25$ °C, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	150	V
V_{GS}	Gate-Source voltage	±20	V
I_D	Continuous drain current@ $V_{GS}=10V$	$T_C=25^\circ C$	A
		$T_A=100^\circ C$	A
I_{DM}	Pulse drain current tested ①	$T_C=25^\circ C$	A
P_D	Maximum power dissipation	$T_C=25^\circ C$	W
I_S	Diode Continuous Forward Current	$T_C=25^\circ C$	A
EAS	Avalanche energy, single pulsed ③	$I_D=3A$	mJ
T_J	Maximum Junction Temperature	175	°C
T_{STG}	Storage temperature range	-55 to 175	°C

Thermal characteristics

$R_{\theta JA}$	Thermal Resistance Junction-Ambient	63	°C/W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	3.0	°C/W

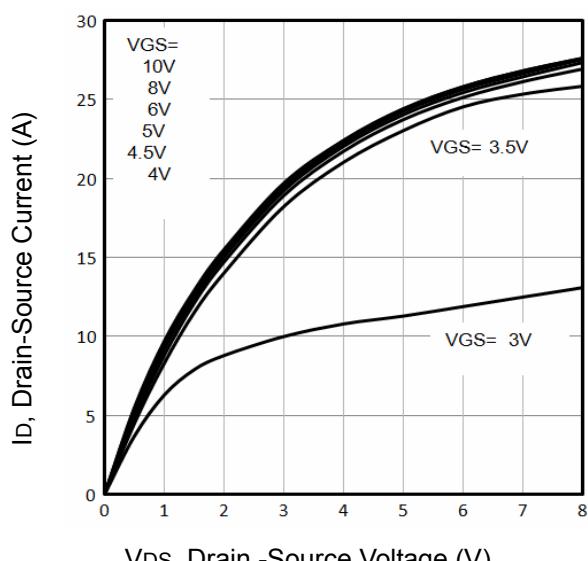
Typical Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	150	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^\circ\text{C}$)	$V_{\text{DS}}=150\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_c=125^\circ\text{C}$)	$V_{\text{DS}}=150\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1.0	2.0	3.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=10\text{V}$, $I_D=10\text{A}$	--	125	140	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=4.5\text{V}$, $I_D=4\text{A}$	--	115	140	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=75\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	1780	--	pF
C_{oss}	Output Capacitance		--	165	--	pF
C_{rss}	Reverse Transfer Capacitance		--	85	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=75\text{V}$, $I_D=6\text{A}$, $V_{\text{GS}}=10\text{V}$	--	39	--	nC
Q_{gs}	Gate-Source Charge		--	10	--	nC
Q_{gd}	Gate-Drain Charge		--	13	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=75\text{V}$, $I_D=1\text{A}$, $R_G=6.8\Omega$, $V_{\text{GS}}=4.5\text{V}$	--	18	--	nS
t_r	Turn-on Rise Time		--	10	--	nS
$t_{\text{d(off)}}$	Turn-Off Delay Time		--	30	--	nS
t_f	Turn-Off Fall Time		--	6	--	nS
Source- Drain Diode Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{\text{SD}}=10\text{ A}$, $V_{\text{GS}}=0\text{V}$	--	0.84	1.20	V
t_{rr}	Reverse Recovery Time	$T_J=25^\circ\text{C}$, $I_{\text{sd}}=4\text{A}$, $V_{\text{GS}}=0\text{V}$ $dI/dt=100\text{A}/\mu\text{s}$	--	45	--	nS
Q_{rr}	Reverse Recovery Charge			385		nC

NOTE:

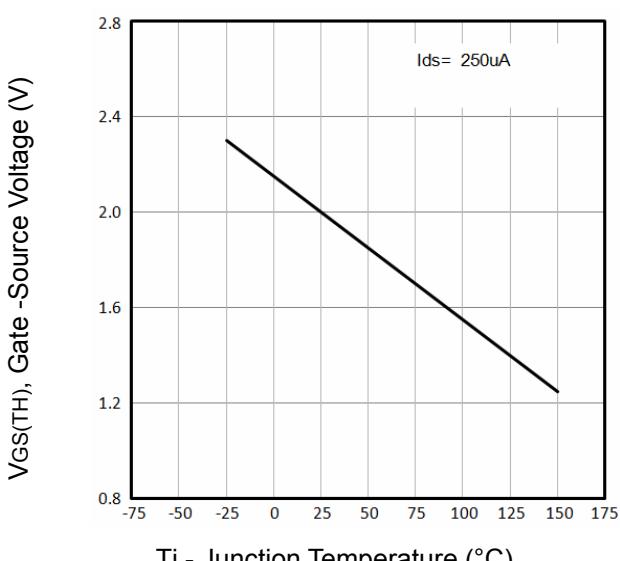
- ① Repetitive rating; pulse width limited by max. junction temperature
- ② Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
- ③ Limited by $T_{J\text{max}}$, starting $T_J = 25^\circ\text{C}$, $L = 0.5\text{mH}$, $R_G = 25\Omega$, $I_{AS} = 3\text{A}$, $V_{GS} = 10\text{V}$. Part not recommended for use above this value

Typical Characteristics



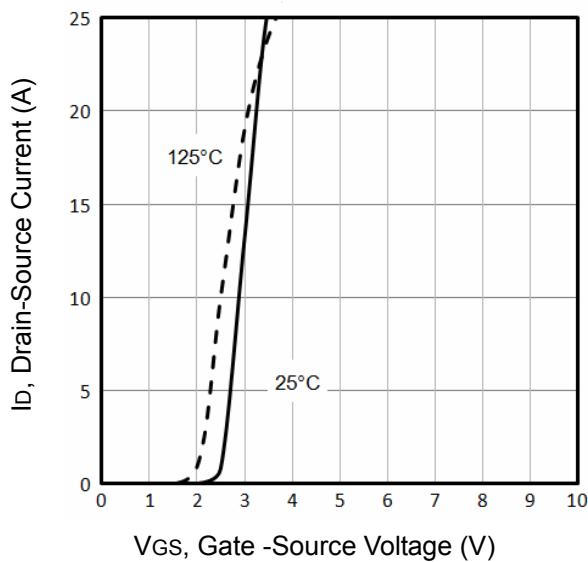
V_{DS}, Drain -Source Voltage (V)

Fig1. Typical Output Characteristics



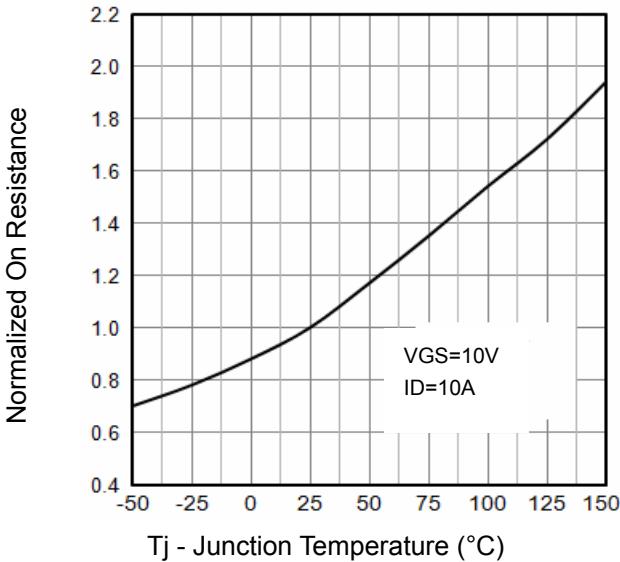
T_j - Junction Temperature (°C)

Fig2. Threshold Voltage Vs. Temperature



V_{GS}, Gate -Source Voltage (V)

Fig3. Typical Transfer Characteristics



T_j - Junction Temperature (°C)

Fig4. Normalized On-Resistance Vs. Temperature

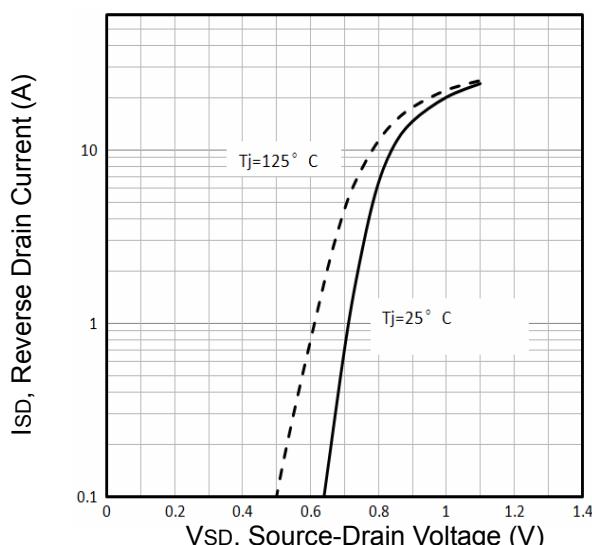


Fig5. Typical Source-Drain Diode Forward Voltage

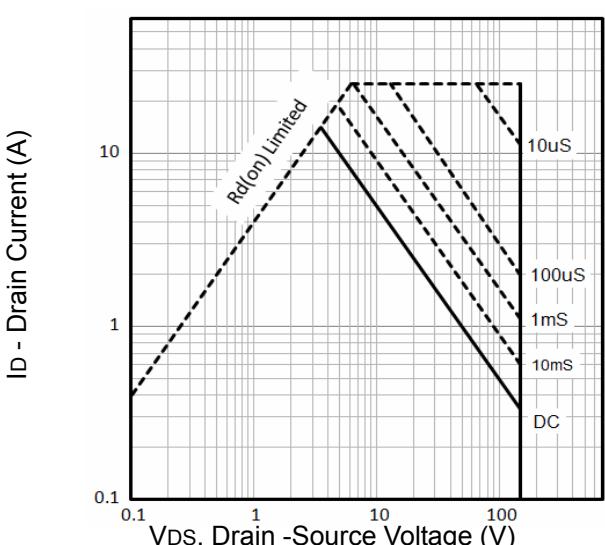


Fig6. Maximum Safe Operating Area

Typical Characteristics

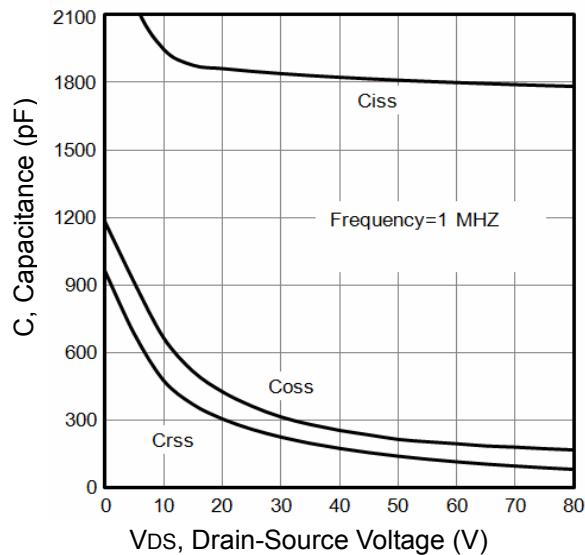


Fig7. Typical Capacitance Vs. Drain-Source Voltage

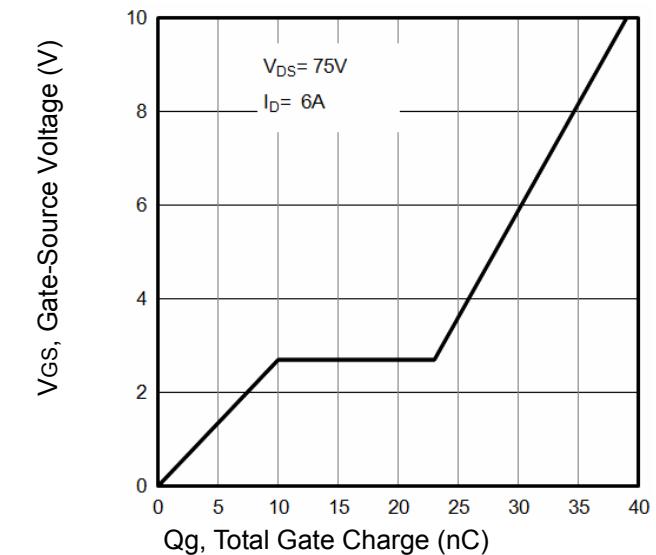


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

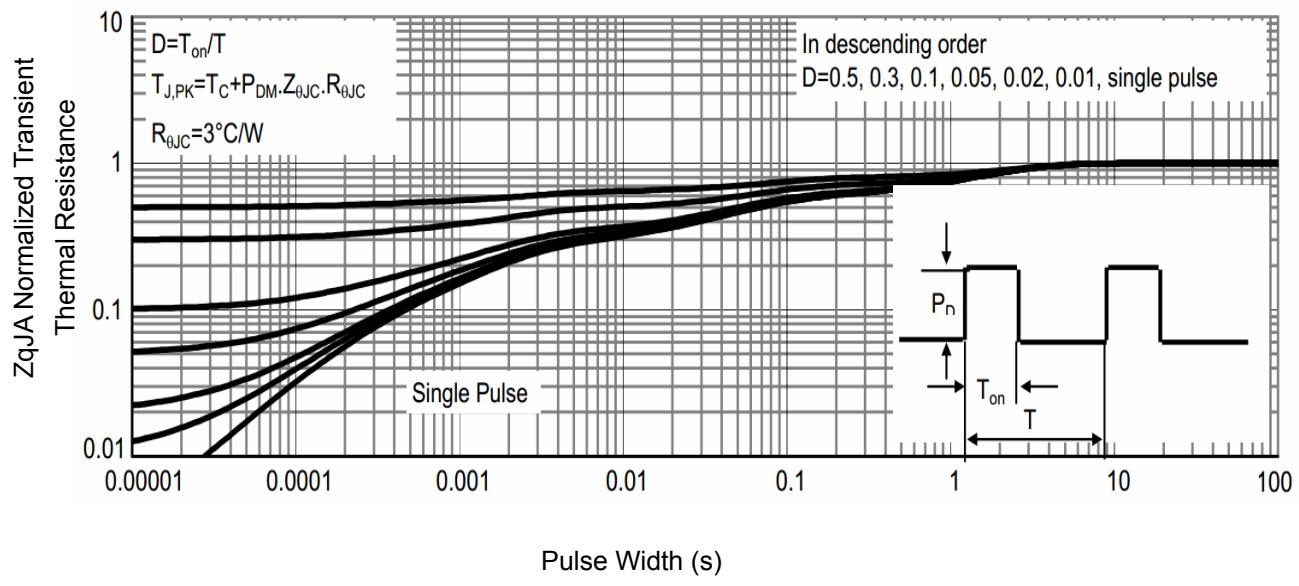


Figure 9: Normalized Maximum Transient Thermal

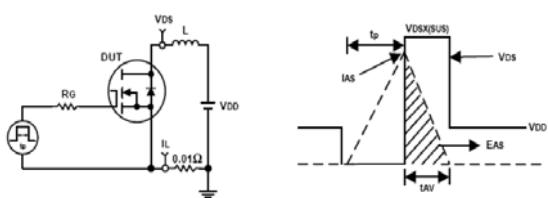


Fig10. Unclamped Inductive Test Circuit and waveforms

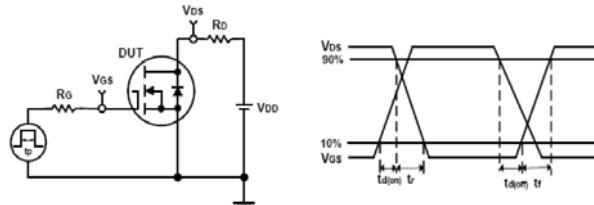
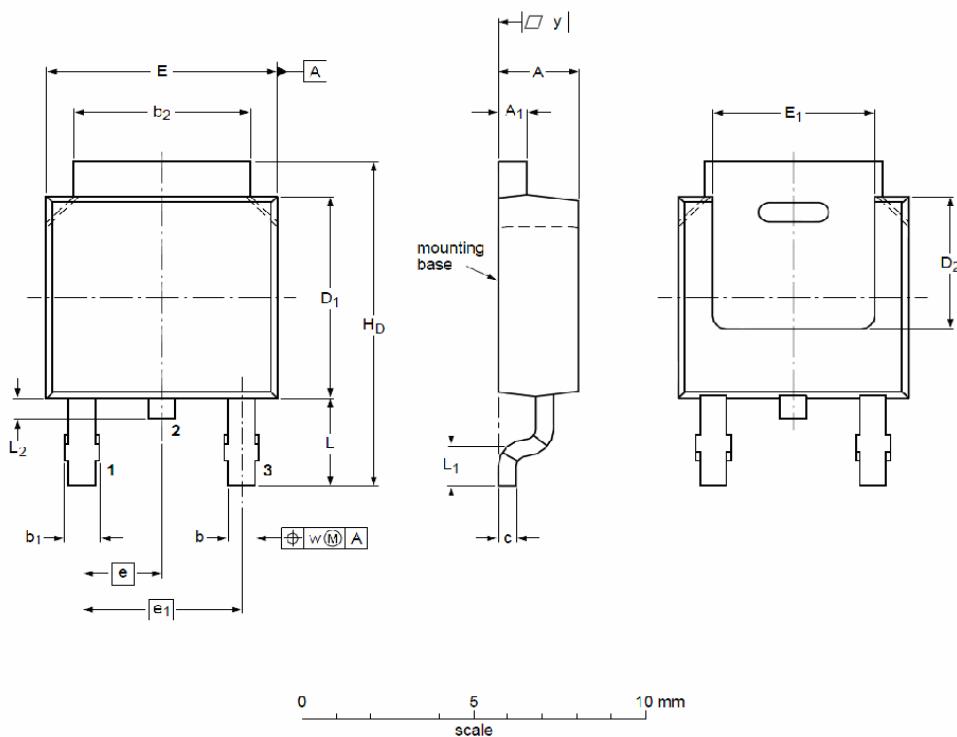


Fig11. Switching Time Test Circuit and waveforms

TO-252 Package Outline



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A ₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b ₁	0.90	0.98	1.10
b ₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D ₁	5.98	6.05	6.22	D ₂	--	4.00	--
E	6.47	6.60	6.73	E ₁	5.10	5.28	5.45
e	--	2.28	--	e ₁	--	4.57	--
H _D	9.60	10.08	10.40	L	2.75	2.95	3.05
L ₁	--	0.50	--	L ₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

Customer Service

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